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Best Product Awards

Jennifer Yario,
Associate Editor

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Asymtek

Axion X-1000 automated fluid dispensing series system was designed for inline semiconductor package and PCB assembly. The series has two components: the Axion X-1010 for SMT application of SMA, solder paste and electrically conductive adhesive applications; and the X-1020 for flip-chip and CSP under-fill applications. The X-1010 uses a DispenseJet valve for non-contact jetting to deliver precise dot volume repeatability without the use of mechanical standoffs. The X-1020 Can be configured for non-contact jetting as well, and features a calibrated process jetting with contact or impingement heating to ensure a reliable thermal environment with pre-dispense, dispense and post-dispense heat stations.

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